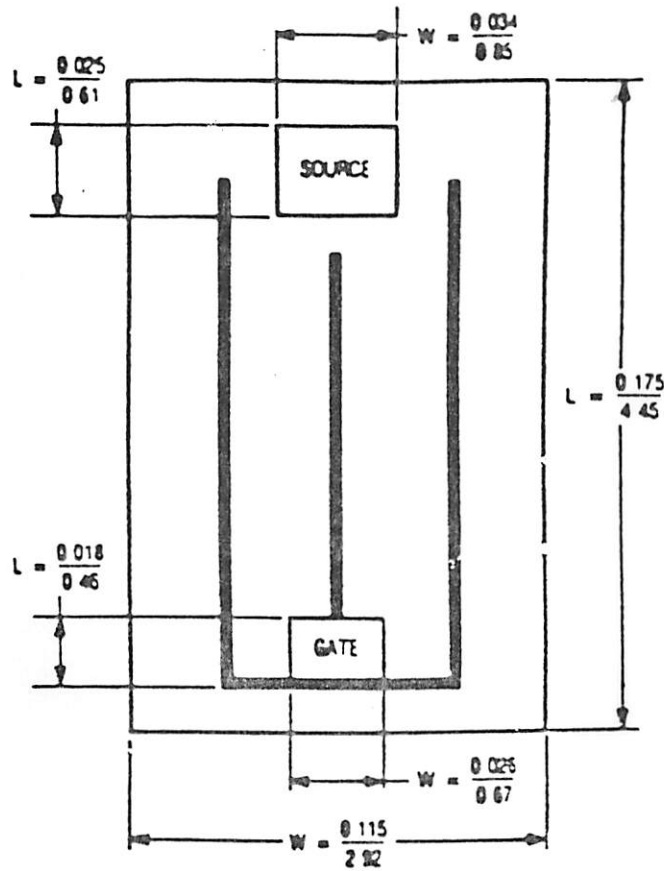




Sierra Components, Inc.

924 Incline Way • Suite F • Incline Village, Nevada 89451
 Phone: 775.831.1241 Fax: 775.831.3021

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below.



Topside Metal: Aluminum
Backside Metal: CrNiAg
Backside Potential: Drain
Mask Ref: Issue 1
Bond Pads (Mils): .004 Min.

APPROVED BY:
MFG: IRI

DIE SIZE: .115" X .175"
THICKNESS: .015"

DATE: 3/21/00
P/N: IRF830

DG 10.1.2
 Rev A 3-4-99